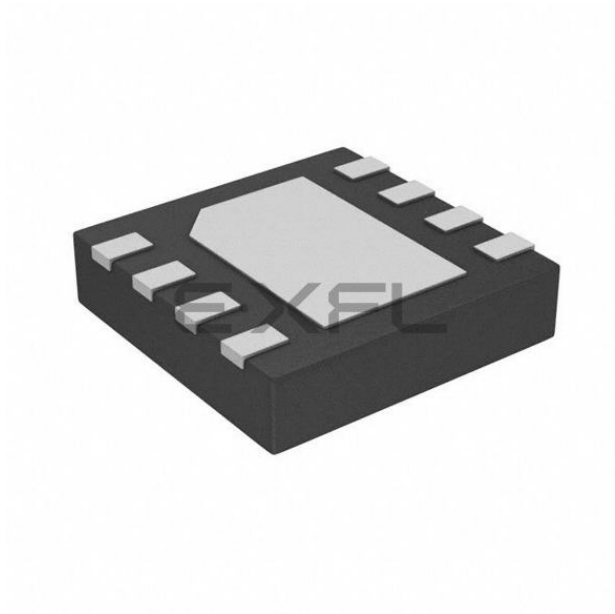

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	6
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 4x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12lf1822t-i-mf

TABLE 3-8: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 8											
400h(1)	INDF0	Addressing this location uses contents of FSR0H/FSR0L to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
401h(1)	INDF1	Addressing this location uses contents of FSR1H/FSR1L to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
402h(1)	PCL	Program Counter (PC) Least Significant Byte								0000 0000	0000 0000
403h(1)	STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	---1 1000	---q quuu
404h(1)	FSR0L	Indirect Data Memory Address 0 Low Pointer								0000 0000	uuuu uuuu
405h(1)	FSR0H	Indirect Data Memory Address 0 High Pointer								0000 0000	0000 0000
406h(1)	FSR1L	Indirect Data Memory Address 1 Low Pointer								0000 0000	uuuu uuuu
407h(1)	FSR1H	Indirect Data Memory Address 1 High Pointer								0000 0000	0000 0000
408h(1)	BSR	—	—	—	BSR<4:0>					---0 0000	---0 0000
409h(1)	WREG	Working Register								0000 0000	uuuu uuuu
40Ah(1)	PCLATH	—	Write Buffer for the upper 7 bits of the Program Counter							-000 0000	-000 0000
40Bh(1)	INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	0000 000x	0000 000u
40Ch	—	Unimplemented								—	—
40Dh	—	Unimplemented								—	—
40Eh	—	Unimplemented								—	—
40Fh	—	Unimplemented								—	—
410h	—	Unimplemented								—	—
411h	—	Unimplemented								—	—
412h	—	Unimplemented								—	—
413h	—	Unimplemented								—	—
414h	—	Unimplemented								—	—
415h	—	Unimplemented								—	—
416h	—	Unimplemented								—	—
417h	—	Unimplemented								—	—
418h	—	Unimplemented								—	—
419h	—	Unimplemented								—	—
41Ah	—	Unimplemented								—	—
41Bh	—	Unimplemented								—	—
41Ch	—	Unimplemented								—	—
41Dh	—	Unimplemented								—	—
41Eh	—	Unimplemented								—	—
41Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, r = reserved.
Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.
2: PIC16(L)F1823 only.
3: Unimplemented. Read as '1'.
4: PIC12(L)F1822 only.

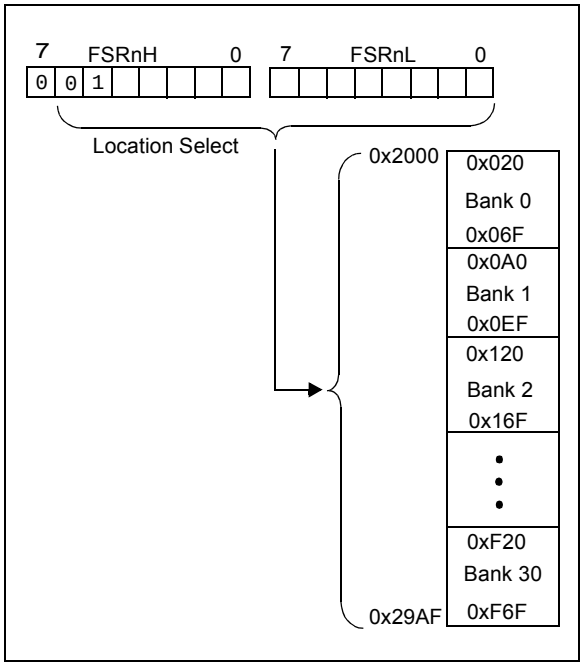
3.5.2 LINEAR DATA MEMORY

The linear data memory is the region from FSR address 0x2000 to FSR address 0x29AF. This region is a virtual region that points back to the 80-byte blocks of GPR memory in all the banks.

Unimplemented memory reads as 0x00. Use of the linear data memory region allows buffers to be larger than 80 bytes because incrementing the FSR beyond one bank will go directly to the GPR memory of the next bank.

The 16 bytes of common memory are not included in the linear data memory region.

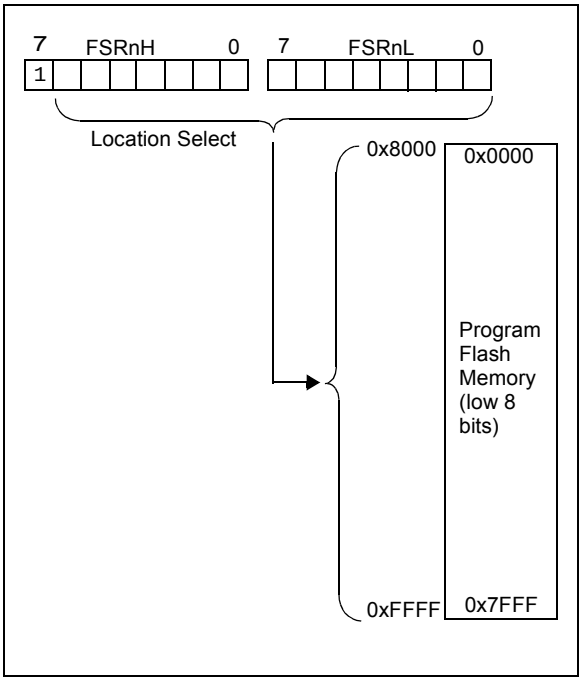
FIGURE 3-10: LINEAR DATA MEMORY MAP



3.5.3 PROGRAM FLASH MEMORY

To make constant data access easier, the entire program Flash memory is mapped to the upper half of the FSR address space. When the MSB of FSRnH is set, the lower 15 bits are the address in program memory which will be accessed through INDF. Only the lower eight bits of each memory location is accessible via INDF. Writing to the program Flash memory cannot be accomplished via the FSR/INDF interface. All instructions that access program Flash memory via the FSR/INDF interface will require one additional instruction cycle to complete.

FIGURE 3-11: PROGRAM FLASH MEMORY MAP



REGISTER 4-2: CONFIGURATION WORD 2

R/P-1/1	R/P-1/1	U-1	R/P-1/1	R/P-1/1	R/P-1/1
LVP(1)	$\overline{\text{DEBUG}}$(2)	—	BORV	STVREN	PLLEN
bit 13					bit 8

U-1	U-1	U-1	R-1	U-1	U-1	R/P-1/1	R/P-1/1
—	—	—	Reserved	—	—	WRT<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13 **LVP:** Low-Voltage Programming Enable bit(1)
1 = Low-voltage programming enabled
0 = High-voltage on $\overline{\text{MCLR}}$ must be used for programming

bit 12 **$\overline{\text{DEBUG}}$:** In-Circuit Debugger Mode bit(2)
1 = In-Circuit Debugger disabled, ICSPCLK and ICSPDAT are general purpose I/O pins
0 = In-Circuit Debugger enabled, ICSPCLK and ICSPDAT are dedicated to the debugger

bit 11 **Unimplemented:** Read as '1'

bit 10 **BORV:** Brown-out Reset Voltage Selection bit(3)
1 = Brown-out Reset voltage (Vbor), low trip point selected
0 = Brown-out Reset voltage (Vbor), high trip point selected

bit 9 **STVREN:** Stack Overflow/Underflow Reset Enable bit
1 = Stack Overflow or Underflow will cause a Reset
0 = Stack Overflow or Underflow will not cause a Reset

bit 8 **PLLEN:** PLL Enable bit
1 = 4xPLL enabled
0 = 4xPLL disabled

bit 7-5 **Unimplemented:** Read as '1'

bit 4 **Reserved:** This location should be programmed to a '1'.

bit 3-2 **Unimplemented:** Read as '1'

bit 1-0 **WRT<1:0>:** Flash Memory Self-Write Protection bits
11 = Write protection off
10 = 000h to 1FFh write-protected, 200h to 7FFh may be modified by EECON control
01 = 000h to 3FFh write-protected, 400h to 7FFh may be modified by EECON control
00 = 000h to 7FFh write-protected, no addresses may be modified by EECON control

Note 1: The LVP bit cannot be programmed to '0' when Programming mode is entered via LVP.
2: The $\overline{\text{DEBUG}}$ bit in Configuration Word is managed automatically by device development tools including debuggers and programmers. For normal device operation, this bit should be maintained as a '1'.
3: See Vbor parameter for specific trip point voltages.

5.2 Clock Source Types

Clock sources can be classified as external or internal.

External clock sources rely on external circuitry for the clock source to function. Examples are: oscillator modules (EC mode), quartz crystal resonators or ceramic resonators (LP, XT and HS modes) and Resistor-Capacitor (RC) mode circuits.

Internal clock sources are contained internally within the oscillator module. The internal oscillator block has two internal oscillators and a dedicated Phase-Locked Loop (HFPLL) that are used to generate three internal system clock sources: the 16 MHz High-Frequency Internal Oscillator (HFINTOSC), 500 kHz (MFINTOSC) and the 31 kHz Low-Frequency Internal Oscillator (LFINTOSC).

The system clock can be selected between external or internal clock sources via the System Clock Select (SCS) bits in the OSCCON register. See **Section 5.3 "Clock Switching"** for additional information.

5.2.1 EXTERNAL CLOCK SOURCES

An external clock source can be used as the device system clock by performing one of the following actions:

- Program the FOSC<2:0> bits in the Configuration Word 1 to select an external clock source that will be used as the default system clock upon a device Reset.
- Write the SCS<1:0> bits in the OSCCON register to switch the system clock source to:
  - Timer1 Oscillator during run-time, or
  - An external clock source determined by the value of the FOSC bits.

See **Section 5.3 "Clock Switching"**for more information.

5.2.1.1 EC Mode

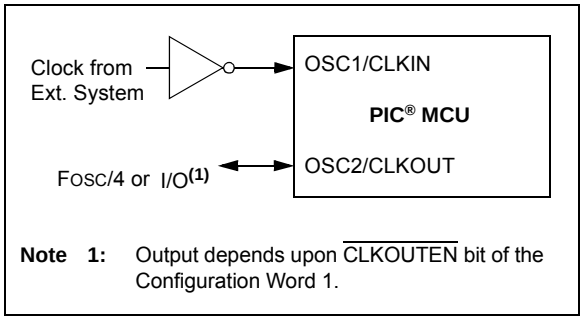
The External Clock (EC) mode allows an externally generated logic level signal to be the system clock source. When operating in this mode, an external clock source is connected to the OSC1 input. OSC2/CLKOUT is available for general purpose I/O or CLKOUT. Figure 5-2 shows the pin connections for EC mode.

EC mode has three power modes to select from through Configuration Word 1:

- High power, 4-32 MHz (FOSC = 111)
- Medium power, 0.5-4 MHz (FOSC = 110)
- Low power, 0-0.5 MHz (FOSC = 101)

The Oscillator Start-up Timer (OST) is disabled when EC mode is selected. Therefore, there is no delay in operation after a Power-on Reset (POR) or wake-up from Sleep. Because the PIC® MCU design is fully static, stopping the external clock input will have the effect of halting the device while leaving all data intact. Upon restarting the external clock, the device will resume operation as if no time had elapsed.

FIGURE 5-2: EXTERNAL CLOCK (EC) MODE OPERATION



Note 1: Output depends upon $\overline{\text{CLKOUTEN}}$ bit of the Configuration Word 1.

5.2.1.2 LP, XT, HS Modes

The LP, XT and HS modes support the use of quartz crystal resonators or ceramic resonators connected to OSC1 and OSC2 (Figure 5-3). The three modes select a low, medium or high gain setting of the internal inverter-amplifier to support various resonator types and speed.

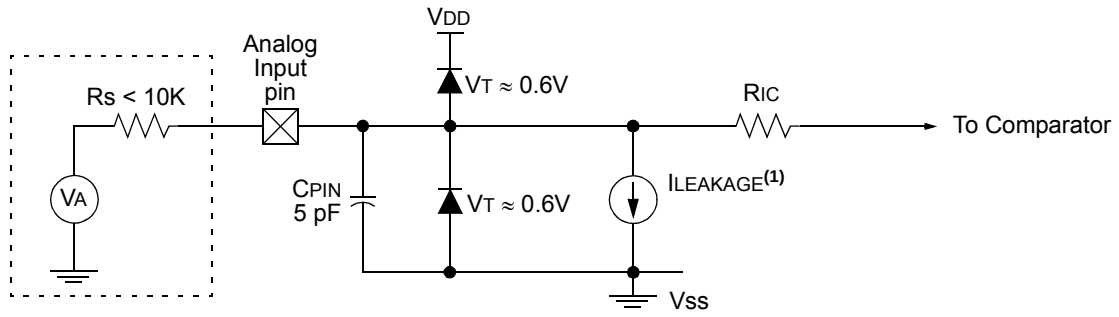
LP Oscillator mode selects the lowest gain setting of the internal inverter-amplifier. LP mode current consumption is the least of the three modes. This mode is designed to drive only 32.768 kHz tuning-fork type crystals (watch crystals).

XT Oscillator mode selects the intermediate gain setting of the internal inverter-amplifier. XT mode current consumption is the medium of the three modes. This mode is best suited to drive resonators with a medium drive level specification.

HS Oscillator mode selects the highest gain setting of the internal inverter-amplifier. HS mode current consumption is the highest of the three modes. This mode is best suited for resonators that require a high drive setting.

Figure 5-3 and Figure 5-4 show typical circuits for quartz crystal and ceramic resonators, respectively.

FIGURE 19-4: ANALOG INPUT MODEL



Legend: CPIN = Input Capacitance
ILEAKAGE = Leakage Current at the pin due to various junctions
RIC = Interconnect Resistance
RS = Source Impedance
VA = Analog Voltage
VT = Threshold Voltage

Note 1: See **Section 30.0 "Electrical Specifications"**

24.1.5 CAPTURE DURING SLEEP

Capture mode depends upon the Timer1 module for proper operation. There are two options for driving the Timer1 module in Capture mode. It can be driven by the instruction clock (FOSC/4), or by an external clock source.

When Timer1 is clocked by FOSC/4, Timer1 will not increment during Sleep. When the device wakes from Sleep, Timer1 will continue from its previous state.

Capture mode will operate during Sleep when Timer1 is clocked by an external clock source.

24.1.6 ALTERNATE PIN LOCATIONS

This module incorporates I/O pins that can be moved to other locations with the use of the alternate pin function register, APFCON. To determine which pins can be moved and what their default locations are upon a Reset, see **Section 12.1 "Alternate Pin Function"** for more information.

TABLE 24-2: SUMMARY OF REGISTERS ASSOCIATED WITH CAPTURE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
APFCON	RXDTSEL	SDOSEL	SSSEL	—	T1GSEL	TXCKSEL	P1BSEL(2)	CCP1SEL(2)	114
CCP1CON	P1M<1:0>		DC1B<1:0>		CCP1M<3:0>				213
CCPR1L	Capture/Compare/PWM Register x Low Byte (LSB)								191
CCPR1H	Capture/Compare/PWM Register x High Byte (MSB)								191
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	86
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	87
PIE2	OSFIE	C2IE(1)	C1IE	EEIE	BCL1IE	—	—	—	88
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	89
PIR2	OSFIF	C2IF(1)	C1IF	EEIF	BCL1IF	—	—	—	90
T1CON	TMR1CS<1:0>		T1CKPS<1:0>		T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON	173
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/DONE	T1GVAL	T1GSS<1:0>		174
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								169
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								169
TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	117
TRISC(1)	—	—	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	121

Legend: — = Unimplemented location, read as '0'. Shaded cells are not used by Capture mode.

Note 1: PIC16(L)F1823 only.

2: PIC12(L)F1822 only.

24.3.2 SETUP FOR PWM OPERATION

The following steps should be taken when configuring the CCP1 module for standard PWM operation:

1. Disable the CCP1 pin output driver by setting the associated TRIS bit.
2. Load the PR2 register with the PWM period value.
3. Configure the CCP1 module for the PWM mode by loading the CCP1CON register with the appropriate values.
4. Load the CCPR1L register and the DC1B1 bits of the CCP1CON register, with the PWM duty cycle value.
5. Configure and start Timer2:
   - Clear the TMR2IF interrupt flag bit of the PIR1 register. See Note below.
   - Configure the T2CKPS bits of the T2CON register with the Timer prescale value.
   - Enable the Timer by setting the TMR2ON bit of the T2CON register.
6. Enable PWM output pin:
   - Wait until the Timer overflows and the TMR2IF bit of the PIR1 register is set. See Note below.
   - Enable the CCP1 pin output driver by clearing the associated TRIS bit.

Note:	In order to send a complete duty cycle and period on the first PWM output, the above steps must be included in the setup sequence. If it is not critical to start with a complete PWM signal on the first output, then step 6 may be ignored.

24.3.3 PWM PERIOD

The PWM period is specified by the PR2 register of Timer2. The PWM period can be calculated using the formula of Equation 24-1.

EQUATION 24-1: PWM PERIOD

$$PWM\ Period = [(PR2) + 1] \bullet 4 \bullet T_{OSC} \bullet (TMR2\ Prescale\ Value)$$

Note 1: TOSC = 1/FOSC

When TMR2 is equal to PR2, the following three events occur on the next increment cycle:

- TMR2 is cleared
- The CCP1 pin is set. (Exception: If the PWM duty cycle = 0%, the pin will not be set.)
- The PWM duty cycle is latched from CCPR1L into CCPR1H.

Note:	The Timer postscaler (see **Section 22.1 "Timer2 Operation"**) is not used in the determination of the PWM frequency.

24.3.4 PWM DUTY CYCLE

The PWM duty cycle is specified by writing a 10-bit value to multiple registers: CCPR1L register and DC1B<1:0> bits of the CCP1CON register. The CCPR1L contains the eight MSbs and the DC1B<1:0> bits of the CCP1CON register contain the two LSbs. CCPR1L and DC1B<1:0> bits of the CCP1CON register can be written to at any time. The duty cycle value is not latched into CCPR1H until after the period completes (i.e., a match between PR2 and TMR2 registers occurs). While using the PWM, the CCPR1H register is read-only.

Equation 24-2 is used to calculate the PWM pulse width.

Equation 24-3 is used to calculate the PWM duty cycle ratio.

EQUATION 24-2: PULSE WIDTH

$$Pulse\ Width = (CCPR1L:CCP1CON<5:4>) \bullet T_{OSC} \bullet (TMR2\ Prescale\ Value)$$

EQUATION 24-3: DUTY CYCLE RATIO

$$Duty\ Cycle\ Ratio = \frac{(CCPRxL:CCPxCON<5:4>)}{4(PRx + 1)}$$

The CCPR1H register and a 2-bit internal latch are used to double buffer the PWM duty cycle. This double buffering is essential for glitchless PWM operation.

The 8-bit timer TMR2 register is concatenated with either the 2-bit internal system clock (FOSC), or two bits of the prescaler, to create the 10-bit time base. The system clock is used if the Timer2 prescaler is set to 1:1.

When the 10-bit time base matches the CCPR1H and 2-bit latch, then the CCP1 pin is cleared (see Figure 24-4).

24.4.2 FULL-BRIDGE MODE (PIC16(L)F1823 ONLY)

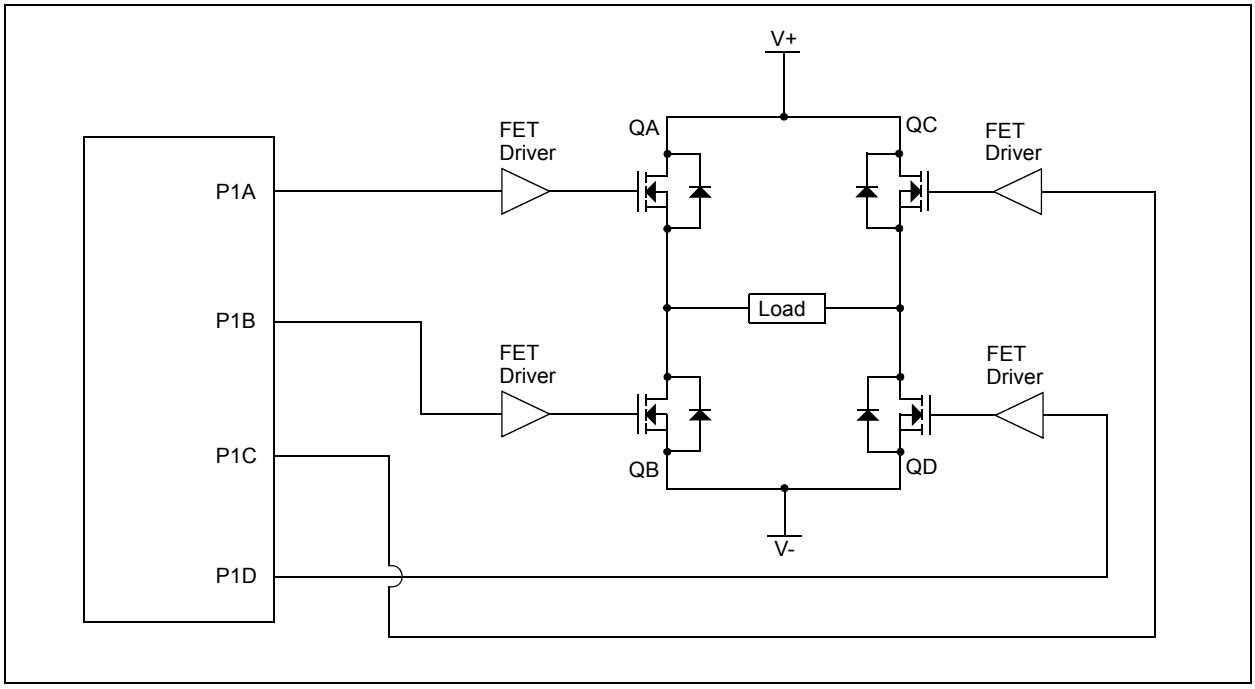
In Full-Bridge mode, all four pins are used as outputs. An example of Full-Bridge application is shown in Figure 24-10.

In the Forward mode, pin CCP1/P1A is driven to its active state, pin P1D is modulated, while P1B and P1C will be driven to their inactive state as shown in Figure 24-11.

In the Reverse mode, P1C is driven to its active state, pin P1B is modulated, while P1A and P1D will be driven to their inactive state as shown Figure 24-11.

P1A, P1B, P1C and P1D outputs are multiplexed with the PORT data latches. The associated TRIS bits must be cleared to configure the P1A, P1B, P1C and P1D pins as outputs.

FIGURE 24-10: EXAMPLE OF FULL-BRIDGE APPLICATION



24.4.3 ENHANCED PWM AUTO-SHUTDOWN MODE

The PWM mode supports an Auto-Shutdown mode that will disable the PWM outputs when an external shutdown event occurs. Auto-Shutdown mode places the PWM output pins into a predetermined state. This mode is used to help prevent the PWM from damaging the application.

The auto-shutdown sources are selected using the CCP1AS<2:0> bits of the CCP1AS register. A shutdown event may be generated by:

- A logic '0' on the FLT0 pin
- A logic '1' on a Comparator (C1) output

A shutdown condition is indicated by the CCP1ASE (Auto-Shutdown Event Status) bit of the CCP1AS register. If the bit is a '0', the PWM pins are operating normally. If the bit is a '1', the PWM outputs are in the shutdown state.

When a shutdown event occurs, two things happen:

The CCP1ASE bit is set to '1'. The CCP1ASE will remain set until cleared in firmware or an auto-restart occurs (see **Section 24.4.4 "Auto-Restart Mode"**).

The enabled PWM pins are asynchronously placed in their shutdown states. The PWM output pins are grouped into pairs [P1A/P1C] and [P1B/P1D]. The state of each pin pair is determined by the PSS1AC and PSS1BD bits of the CCP1AS register. Each pin pair may be placed into one of three states:

- Drive logic '1'
- Drive logic '0'
- Tri-state (high-impedance)

Note 1: The auto-shutdown condition is a level-based signal, not an edge-based signal. As long as the level is present, the auto-shutdown will persist.

2: Writing to the CCP1ASE bit is disabled while an auto-shutdown condition persists.

3: Once the auto-shutdown condition has been removed and the PWM restarted (either through firmware or auto-restart) the PWM signal will always restart at the beginning of the next PWM period.

4: Prior to an auto-shutdown event caused by a comparator output or FLT0 pin event, a software shutdown can be triggered in firmware by setting the CCP1ASE bit of the CCP1AS register to '1'. The auto-restart feature tracks the active status of a shutdown caused by a comparator output or FLT0 pin event only. If it is enabled at this time, it will immediately clear this bit and restart the ECCP module at the beginning of the next PWM period.

FIGURE 24-14: PWM AUTO-SHUTDOWN WITH FIRMWARE RESTART (P1RSEN = 0)

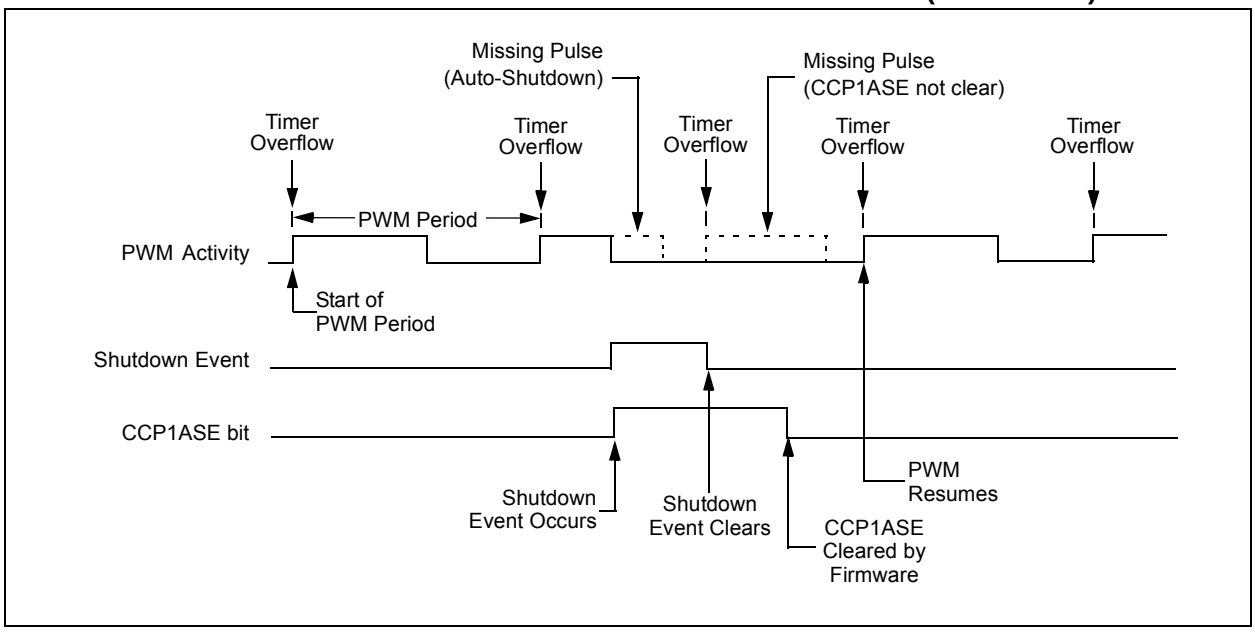
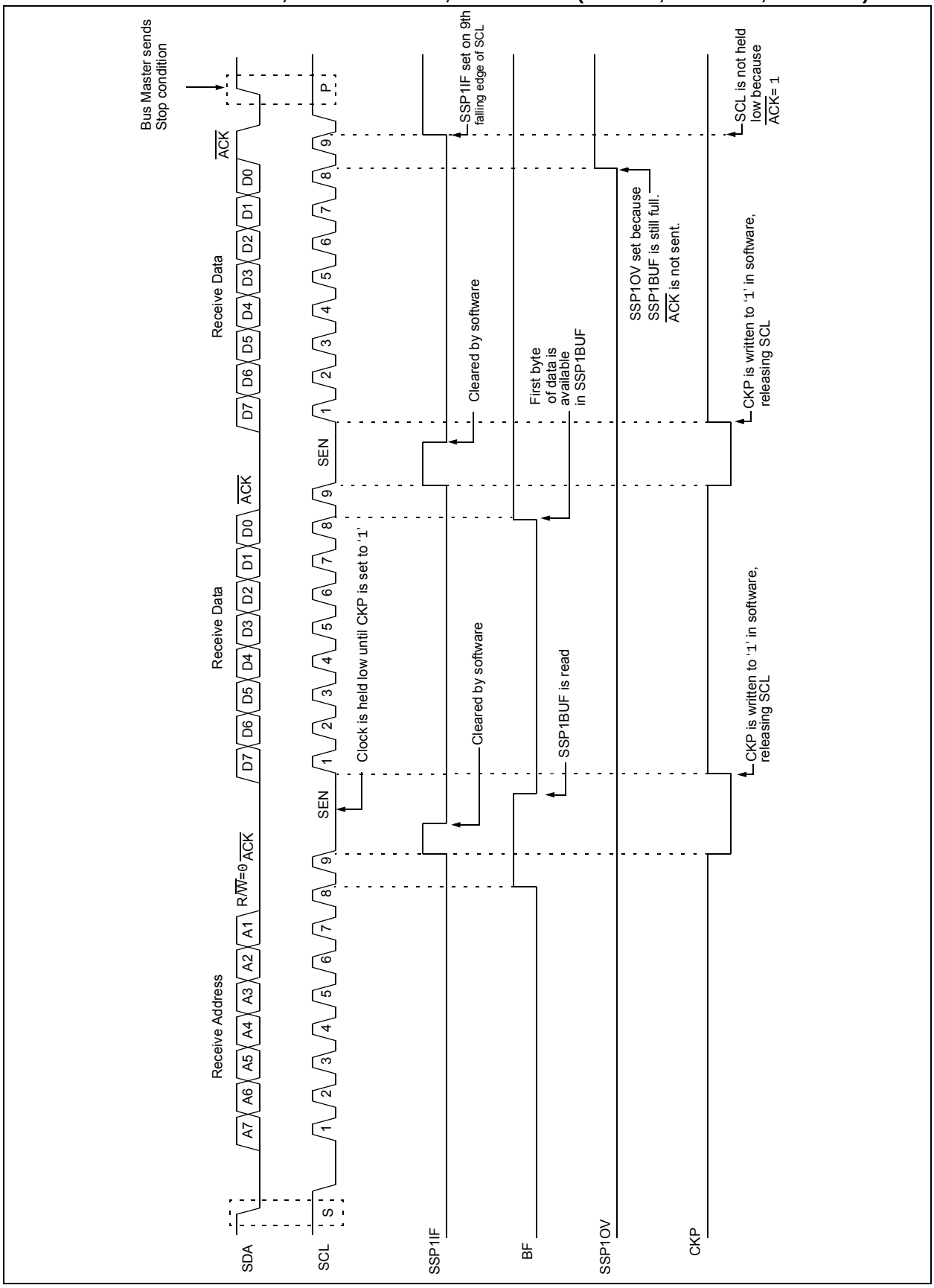


FIGURE 25-15: I²C SLAVE, 7-BIT ADDRESS, RECEPTION (SEN = 1, AHEN = 0, DHEN = 0)



25.6.8 ACKNOWLEDGE SEQUENCE TIMING

An Acknowledge sequence is enabled by setting the Acknowledge Sequence Enable bit, ACKEN bit of the SSP1CON2 register. When this bit is set, the SCL pin is pulled low and the contents of the Acknowledge data bit are presented on the SDA pin. If the user wishes to generate an Acknowledge, then the ACKDT bit should be cleared. If not, the user should set the ACKDT bit before starting an Acknowledge sequence. The Baud Rate Generator then counts for one rollover period (TBRG) and the SCL pin is deasserted (pulled high). When the SCL pin is sampled high (clock arbitration), the Baud Rate Generator counts for TBRG. The SCL pin is then pulled low. Following this, the ACKEN bit is automatically cleared, the Baud Rate Generator is turned off and the MSSP1 module then goes into Idle mode (Figure 25-30).

25.6.8.1 WCOL Status Flag

If the user writes the SSP1BUF when an Acknowledge sequence is in progress, then WCOL is set and the contents of the buffer are unchanged (the write does not occur).

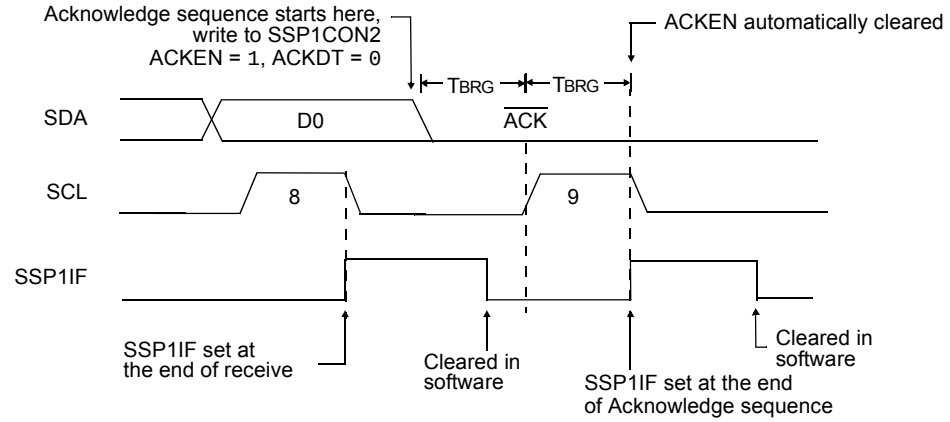
25.6.9 STOP CONDITION TIMING

A Stop bit is asserted on the SDA pin at the end of a receive/transmit by setting the Stop Sequence Enable bit, PEN bit of the SSP1CON2 register. At the end of a receive/transmit, the SCL line is held low after the falling edge of the ninth clock. When the PEN bit is set, the master will assert the SDA line low. When the SDA line is sampled low, the Baud Rate Generator is reloaded and counts down to '0'. When the Baud Rate Generator times out, the SCL pin will be brought high and one TBRG (Baud Rate Generator rollover count) later, the SDA pin will be deasserted. When the SDA pin is sampled high while SCL is high, the P bit of the SSP1STAT register is set. A TBRG later, the PEN bit is cleared and the SSP1IF bit is set (Figure 25-31).

25.6.9.1 WCOL Status Flag

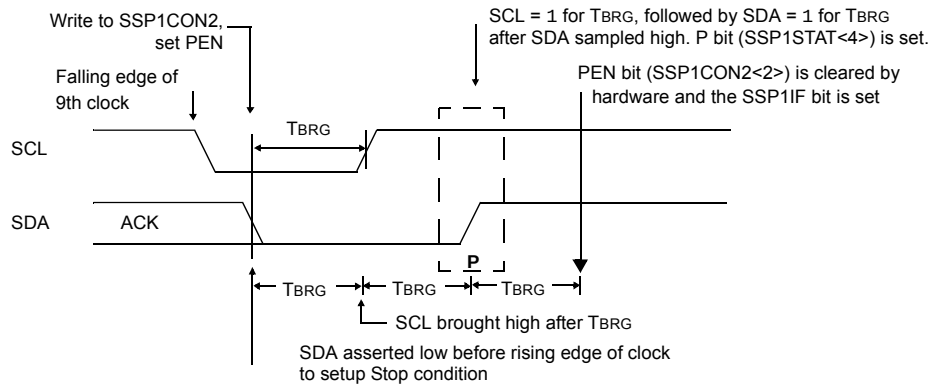
If the user writes the SSP1BUF when a Stop sequence is in progress, then the WCOL bit is set and the contents of the buffer are unchanged (the write does not occur).

FIGURE 25-30: ACKNOWLEDGE SEQUENCE WAVEFORM



Note: TBRG = one Baud Rate Generator period.

FIGURE 25-31: STOP CONDITION RECEIVE OR TRANSMIT MODE



Note: TBRG = one Baud Rate Generator period.

27.7.3 FREQUENCY THRESHOLD

The frequency threshold should be placed midway between the value of nominal frequency and the reduced frequency of the capacitive sensing oscillator. Refer to Application Note AN1103, "*Software Handling for Capacitive Sensing*" (DS01103) for more detailed information on the software required for CPS module.

Note:	For more information on general capacitive sensing refer to Application Notes: • AN1101, "*Introduction to Capacitive Sensing*" (DS01101) • AN1102, "*Layout and Physical Design Guidelines for Capacitive Sensing*" (DS01102)

27.8 Operation during Sleep

The capacitive sensing oscillator will continue to run as long as the module is enabled, independent of the part being in Sleep. In order for the software to determine if a frequency change has occurred, the part must be awake. However, the part does not have to be awake when the timer resource is acquiring counts.

Note:	Timer0 does not operate when in Sleep, and therefore cannot be used for capacitive sense measurements in Sleep.

RRF **Rotate Right f through Carry**

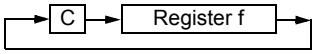
Syntax: [*label*] RRF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: See description below

Status Affected: C

Description: The contents of register 'f' are rotated one bit to the right through the Carry flag. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.



SLEEP **Enter Sleep mode**

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT,
0 → WDT prescaler,
1 → $\overline{TO}$,
0 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Description: The power-down Status bit, $\overline{PD}$ is cleared. Time-out Status bit, $\overline{TO}$ is set. Watchdog Timer and its prescaler are cleared.
The processor is put into Sleep mode with the oscillator stopped.

SUBLW **Subtract W from literal**

Syntax: [*label*] SUBLW k

Operands: $0 \le k \le 255$

Operation: k - (W) → (W)

Status Affected: C, DC, Z

Description: The W register is subtracted (2's complement method) from the 8-bit literal 'k'. The result is placed in the W register.

C = 0	W > k
C = 1	W ≤ k
DC = 0	W<3:0> > k<3:0>
DC = 1	W<3:0> ≤ k<3:0>

SUBWF **Subtract W from f**

Syntax: [*label*] SUBWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - (W) → (destination)

Status Affected: C, DC, Z

Description: Subtract (2's complement method) W register from register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f.

C = 0	W > f
C = 1	W ≤ f
DC = 0	W<3:0> > f<3:0>
DC = 1	W<3:0> ≤ f<3:0>

SUBWFB **Subtract W from f with Borrow**

Syntax: SUBWFB f {,d}

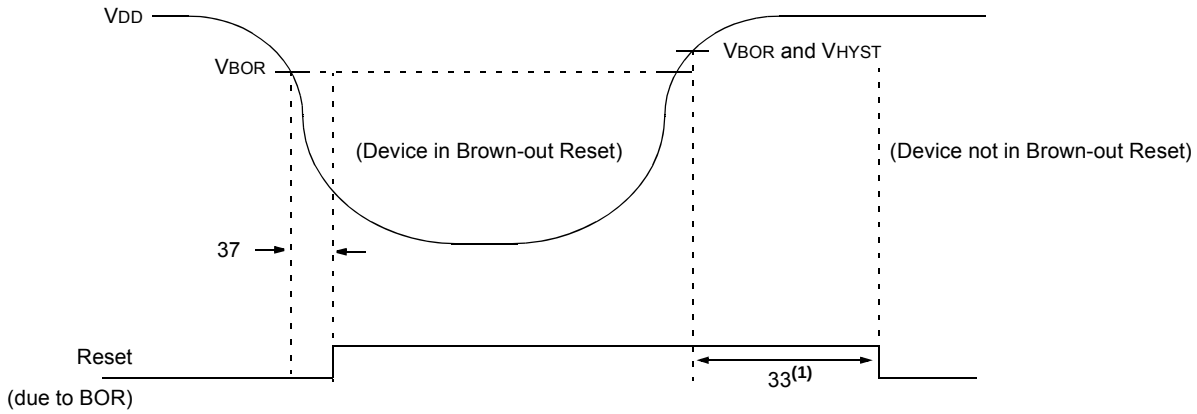
Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) – (W) – ($\overline{B}$) → dest

Status Affected: C, DC, Z

Description: Subtract W and the BORROW flag (CARRY) from register 'f' (2's complement method). If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f'.

FIGURE 30-9: BROWN-OUT RESET TIMING AND CHARACTERISTICS

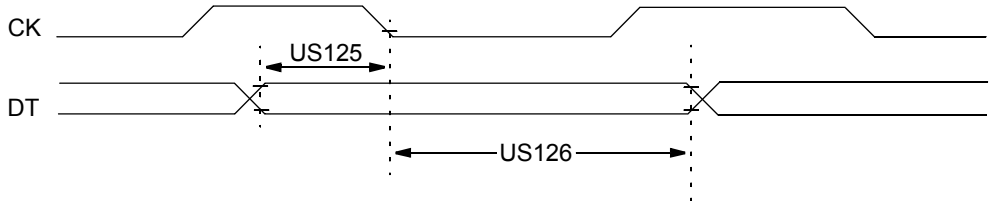


Note 1: 64 ms delay only if $\overline{\text{PWRTE}}$ bit in the Configuration Word 1 is programmed to '0'.
2 ms delay if $\overline{\text{PWRTE}}$ = 0.

TABLE 30-12: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C							
Param. No.	**Symbol**	**Characteristic**		**Min.**	**Max.**	**Units**	**Conditions**
US120	TCKH2DTV	SYNC XMIT (Master and Slave) Clock high to data-out valid	3.0-5.5V	—	80	ns	
			1.8-5.5V	—	100	ns	
US121	TCKRF	Clock out rise time and fall time (Master mode)	3.0-5.5V	—	45	ns	
			1.8-5.5V	—	50	ns	
US122	TDTRF	Data-out rise time and fall time	3.0-5.5V	—	45	ns	
			1.8-5.5V	—	50	ns	

FIGURE 30-15: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 30-5 for load conditions.

TABLE 30-13: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C						
Param. No.	**Symbol**	**Characteristic**	**Min.**	**Max.**	**Units**	**Conditions**
US125	TDTV2CKL	SYNC RCV (Master and Slave) Data-hold before CK ↓ (DT hold time)	10	—	ns	
US126	TCKL2DTL	Data-hold after CK ↓ (DT hold time)	15	—	ns	

FIGURE 31-17: IDDTYPICAL, EC OSCILLATOR, HIGH-POWER MODE, PIC12F1822 AND PIC16F1823 ONLY

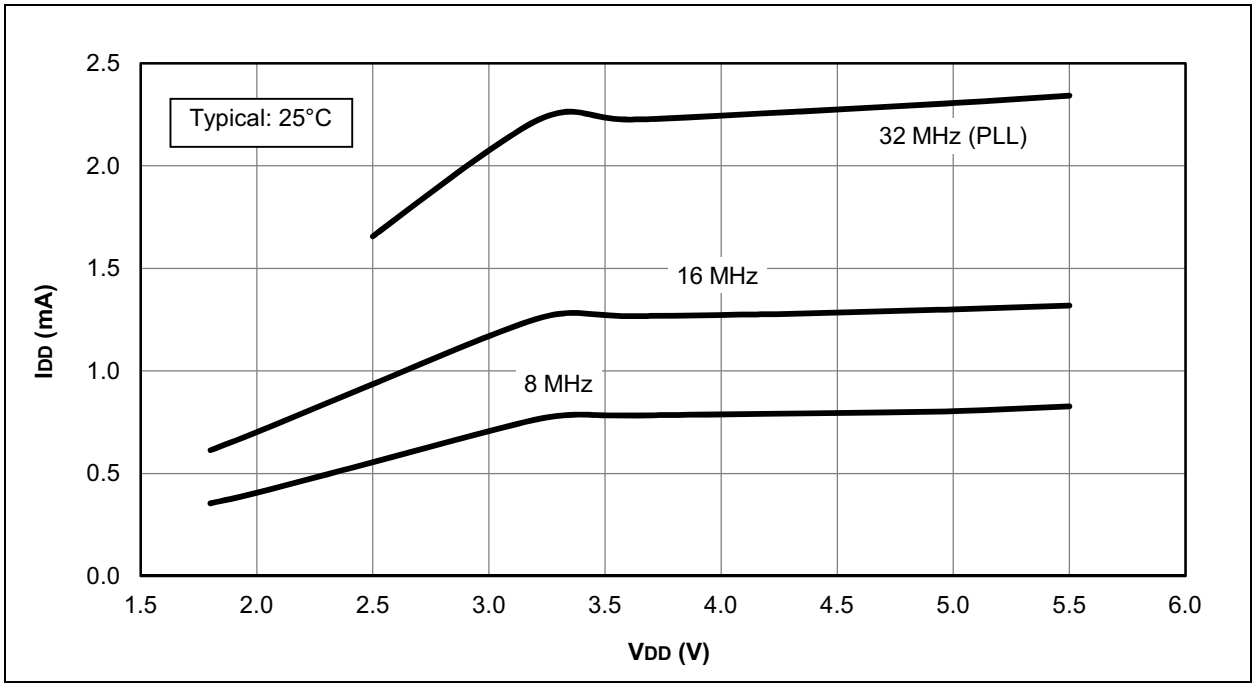


FIGURE 31-18: IDD MAXIMUM, EC OSCILLATOR, HIGH-POWER MODE, PIC12F1822 AND PIC16F1823 ONLY

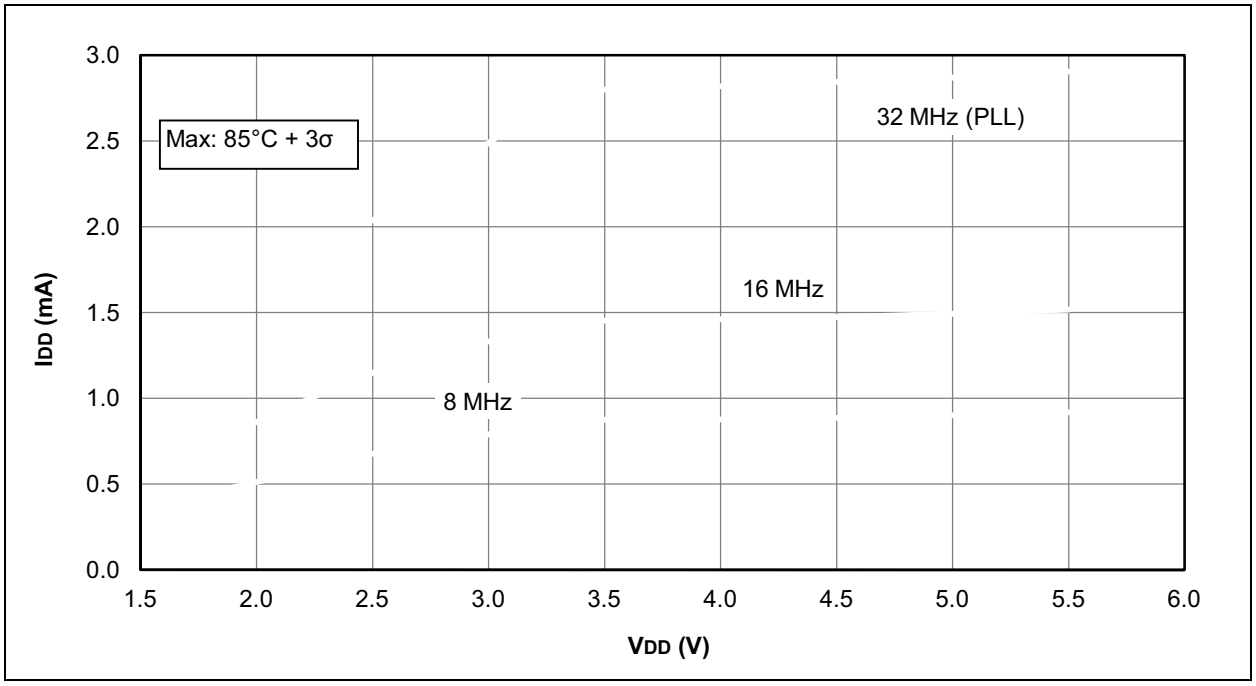


FIGURE 31-40: I_{PD}, COMPARATOR, LOW-POWER MODE (CxSP = 0), PIC12LF1822 AND PIC16LF1823 ONLY

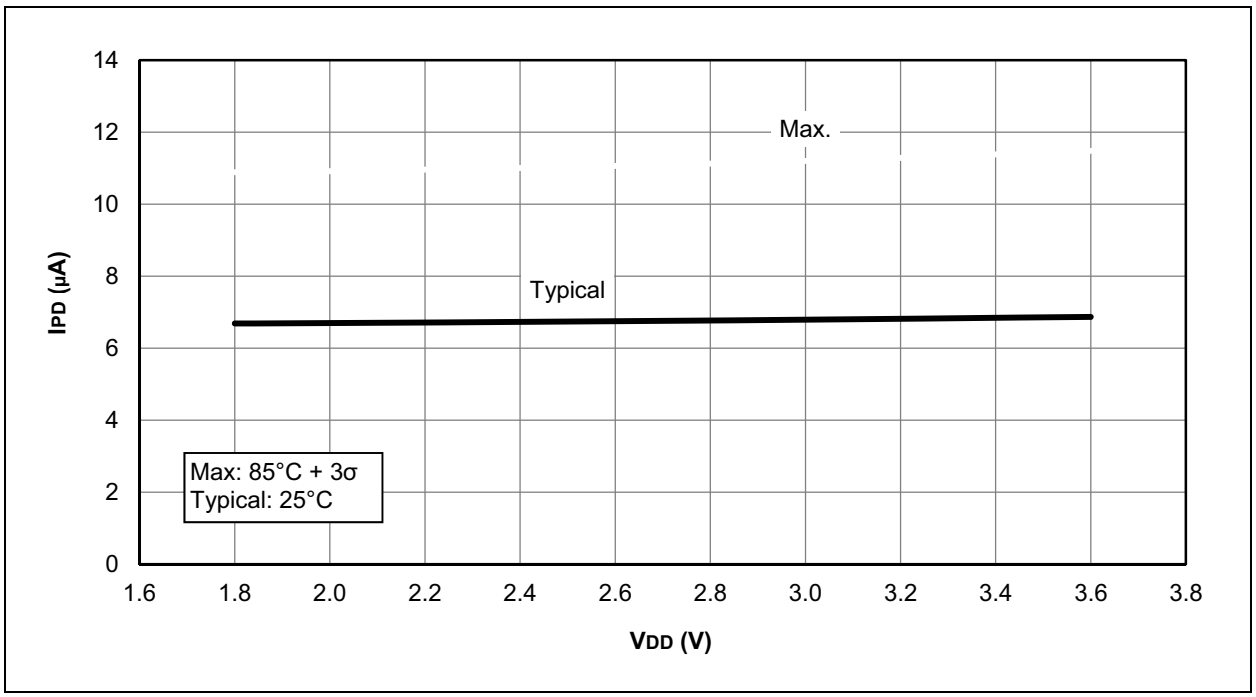


FIGURE 31-41: I_{PD}, COMPARATOR, LOW-POWER MODE (CxSP = 0), PIC12F1822 AND PIC16F1823 ONLY

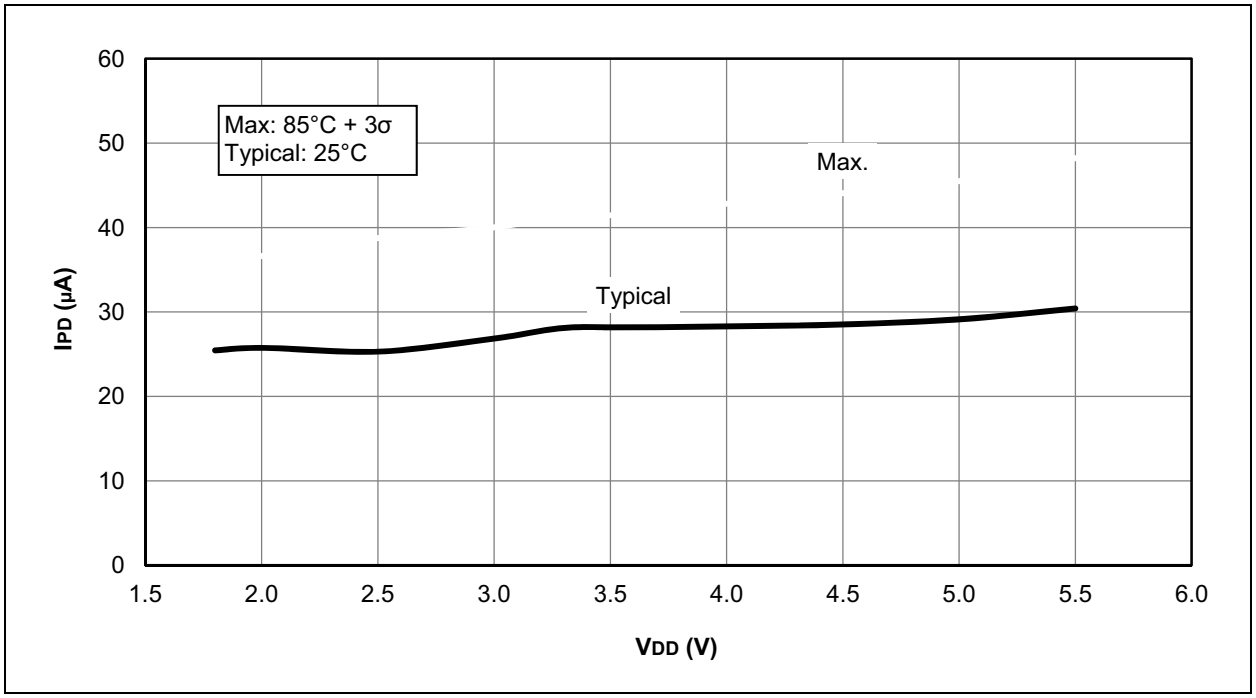


FIGURE 31-44: POR RELEASE VOLTAGE

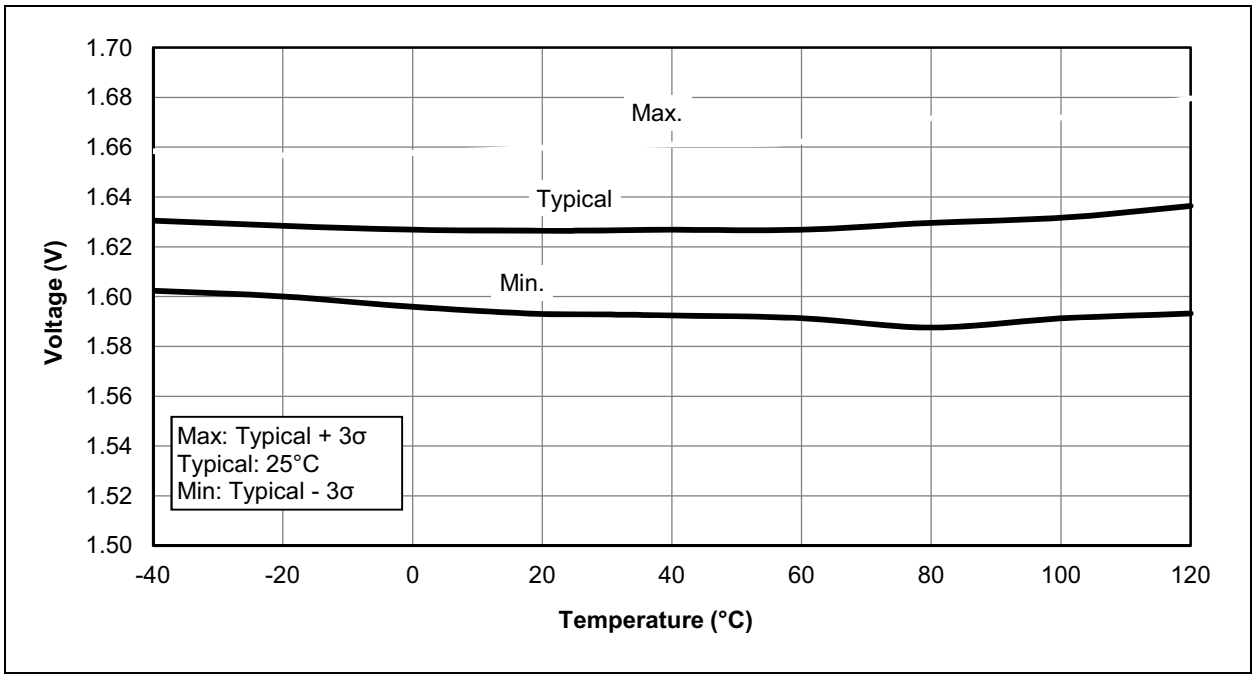
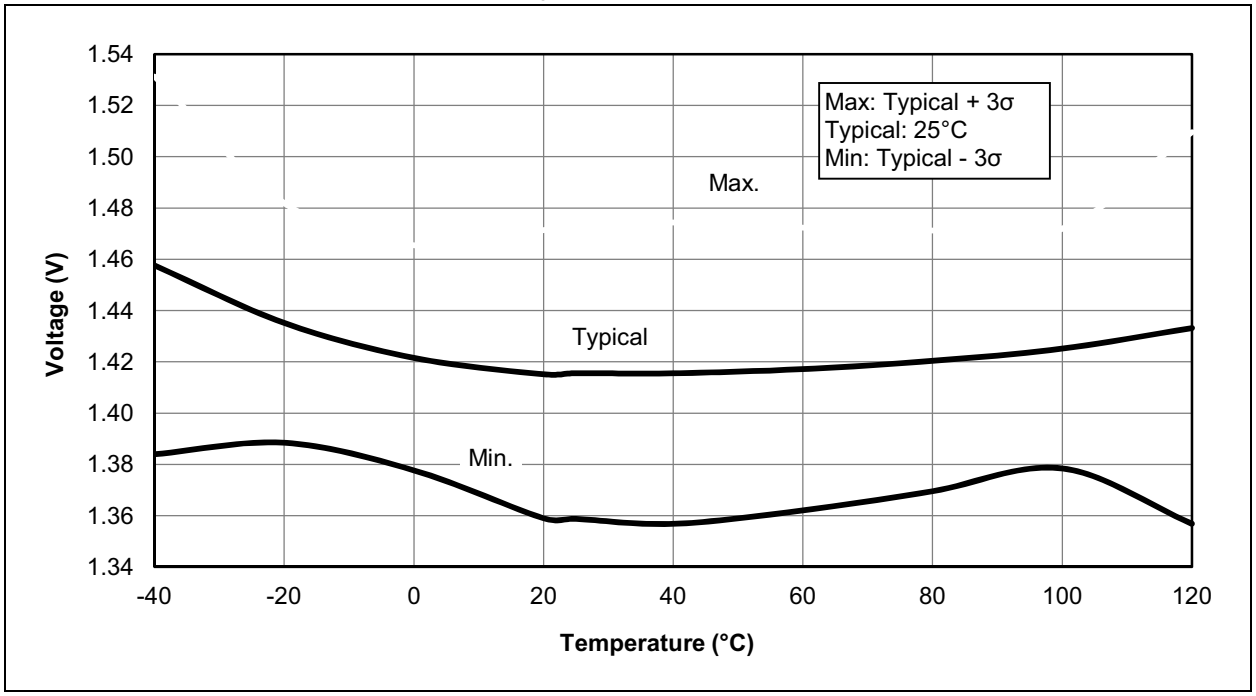
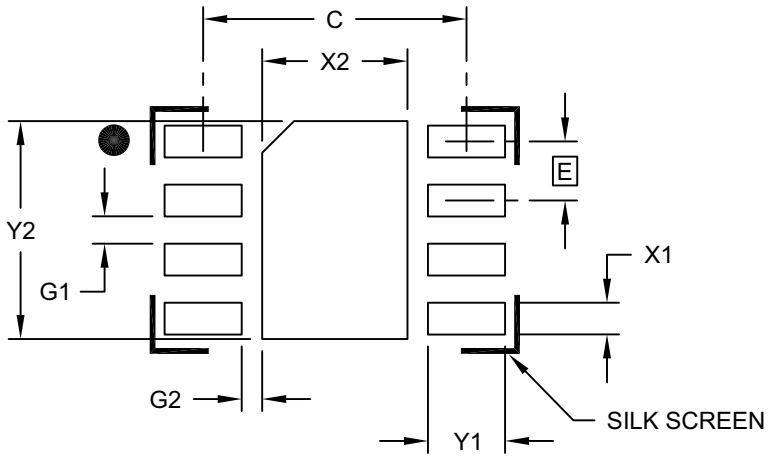


FIGURE 31-45: POR REARM VOLTAGE, PIC12F1822 AND PIC16F1823 ONLY



8-Lead Ultra Thin Plastic Dual Flat, No Lead Package (RF) - 3x3x0.50 mm Body [UDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	X2			1.60
Optional Center Pad Length	Y2			2.40
Contact Pad Spacing	C		2.90	
Contact Pad Width (X8)	X1			0.35
Contact Pad Length (X8)	Y1			0.85
Contact Pad to Contact Pad (X6)	G1	0.20		
Contact Pad to Center Pad (X8)	G2	0.30		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

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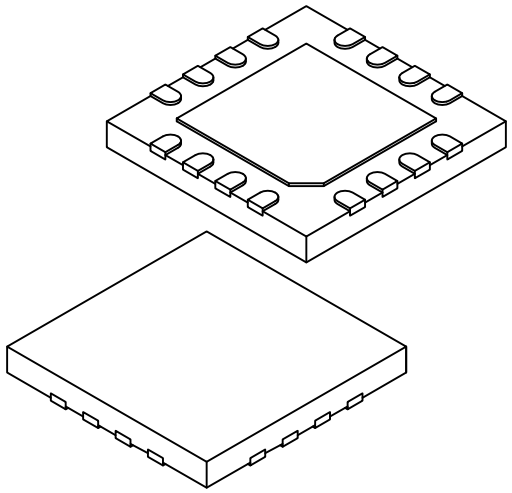
14-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

16-Lead Ultra Thin Plastic Quad Flat, No Lead Package (JQ) - 4x4x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		16	
Pitch	e		0.65 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.127 REF	
Overall Width	E		4.00 BSC	
Exposed Pad Width	E2	2.50	2.60	2.70
Overall Length	D		4.00 BSC	
Exposed Pad Length	D2	2.50	2.60	2.70
Terminal Width	b	0.25	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-257A Sheet 2 of 2